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J.Wm.

TESSERA 3.3-018 CONT CONT 2 DIV.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Applicant of
Khandros et al.

Divisional Application of
Prior Application Serial No. 08/861,280

Filed: Herewith

For: SEMICONDUCTOR CHIP ASSEMBLIES,
METHODS OF MAKING SAME AND
COMPONENTS FOR SAME

Group Art Unit:

Examiner:

Date: December 3, 1997

X

Assistant Commissioner For Patents
Box Patent Application
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

After according a filing date to the above-identified Rule 53(b)

Divisional Application, please amend the application as follows:

In the Claims:

Cancel claims 1-60.

Insert new claims 61-70 as follows:

61. A semiconductor chip assembly comprising:

(a) a semiconductor chip having a front surface defining the top of the chip, said front surface including a central region and a peripheral region surrounding said central region, whereby said central region is disposed inwardly of said peripheral region, said chip having central contacts disposed in said central region

EXPRESS MAIL LABEL NUMBER: EM105971946US

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